

R283-S93-AAF1

Rack Server - 2U DP 2 x PCIe Gen5 GPUs 2400W

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Features

- NVIDIA-Certified Systems™ - Data Center Servers
- Supports up to 2 x Dual slot Gen5 GPUs
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture supported
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 3.5"/2.5" Gen4 NVMe/SATA/SAS hot-swappable bays
- 8 x 3.5"/2.5" SATA/SAS hot-swappable bays
- 2 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x FHHL PCIe Gen5 x16 slots
- 4 x LP PCIe Gen5 x8 slots
- 2 x OCP 3.0 Gen5 x16 slots
- Dual 2400W 80 PLUS Platinum redundant power supply

Specification

Dimensions	2U (W438 x H87.5 x D815 mm)	Backplane Board	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
Motherboard	MS93-FS0	Power Supply	Dual 2400W 80 PLUS Platinum redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP 350W at ambient 25°C	System Management	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Socket	2 x LGA 4677 (Socket E)	OS Compatibility	Windows Server 2019 / 2022 RHEL 8.6 / 8.7 / 8.8 / 8.9 / 8.10 / 9.0 / 9.1 / 9.2 / 9.3 / 9.4 SLES 15 SP4 / SP5 / SP6 Ubuntu 22.04 / 22.04.1 / 22.04.2 / 22.04.3 / 22.04.4 / 24.04 LTS VMware ESXi 7.0 Update 3o / 8.0 Update 1, Update 2, Update 3 Citrix Hypervisor 8.2 LTSR CU1
Chipset	Intel® C741 Chipset	System Fans	4 x 80x80x38mm (18,300rpm)
Memory	32 x DIMM slots, 8-Channel DDR5 memory RDIMM up to 96GB supported 3DS RDIMM up to 256GB supported Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC)	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
LAN	2 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Supported NCSI 1 x 10/100/1000 management LAN	Packaging Content	1 x R283-S93-AAF1, 2 x CPU heatsinks, 6 x Carrier clips, 1 x Mini-DP to D-Sub cable, 1 x 2-Section Rail kit 2 x GPU power cables (CPU 8pin, 350mm) Packaging Dimensions: 1077 x 679 x 300 mm
Video	ASPEED® AST2600 Integrated 2D Graphic Adapter	Part Numbers	Barebone package (5th/4th Gen): 6NR283S93DR000ABF1* Barebone package (4th Gen): 6NR283S93DR000AAF1* - 2-Section Rail kit (CMA not supported): 25HB2-3A0206-K0R - CPU heatsink: 25ST1-323208-A0R - Mini-DP to D-Sub cable: 25CRN-200801-K1R - GPU power cable (CPU 8pin, 350mm): 25CRI-350100-Y4R - Power supply: 25EP0-224000-D0S - C19 power cord 125V/15A (US): 25CP1-018000-Q0R (Optional) - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R (Optional) - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R (Optional)
Storage	4 x 3.5"/2.5" Gen4 NVMe/SATA/SAS hot-swappable bays 8 x 3.5"/2.5" SATA/SAS hot-swappable bays *SAS card is required for SAS devices support		
RAID	Intel® SATA RAID 0/1/10/5		
Expansion Slots	2 x FHFL PCIe Gen5 x16 slots for GPUs 2 x FHHL PCIe Gen5 x16 slots 4 x LP PCIe Gen5 x8 slots 2 x OCP 3.0 Gen5 x16 slots - Supporte NCSI function		
TPM	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)		
I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector		



Learn more at <https://www.GIGABYTE.com/enterprise>

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